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Micro-four-point probe Hall effect measurement method

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We report a new microscale Hall effect measurement method for characterization of semiconductor thin films without need for conventional Hall effect geometries and metal contact pads. We derive the electrostatic potential resulting from current flow in a conductive filamentary sheet with insulating barriers and with a magnetic field applied normal to the plane of the sheet. Based on this potential, analytical expressions for the measured four-point resistance in presence of a magnetic field are derived for several simple sample geometries. We show how the sheet resistance and Hall effect contributions may be separated using dual configuration measurements. The method differs from conventional van der Pauw measurements since the probe pins are placed in the interior of the sample region, not just on the perimeter. We experimentally verify the method by micro-four-point probe measurements on ultrashallow junctions in silicon and germanium. On a cleaved silicon ultrashallow junction sample we determine carrier mobility, sheet carrier density, and sheet resistance from micro-four-point probe measurements under various experimental conditions, and show with these conditions reproducibility within less than 1.5%. © 2008 American Institute of Physics. [DOI: 10.1063/1.2949401]

I. INTRODUCTION

In processing of semiconductor devices a wide range of analytical techniques are applied for process control and characterization,1 which is essential due to the very high complexity of the full process flow and due to the high costs involved. Process control and characterization will become even more important and difficult in the future due to the continued scaling of, e.g., complementary metal–oxide–semiconductor (CMOS) processes. In these CMOS processes extremely shallow (<20 nm) source/drain extensions with very high carrier concentration and high carrier mobility are required.2 Several techniques are applied for characterization of activated ion-implanted shallow junctions; some of these require specialized sample preparation others are destructive or require delicate calibration.4 Among the parameters that must be characterized are sheet resistance, sheet carrier density, and carrier mobility. Four-point probes are widely used for sheet resistance characterization since essentially no additional sample preparation is necessary.4 It has recently been shown that micro-four-point probes are able to accurately measure sheet resistance of ultrashallow junctions with high spatial resolution4 and without artifacts due to probe penetration6 and leakage current,6 moreover carrier profiling on beveled ultrashallow junctions has been demonstrated.7,8

The implantation and annealing processes used in semiconductor fabrication today cannot guarantee 100% activation of the implanted dose, and defects not removed by annealing may lead to reduced carrier mobility.9 While sheet resistance only, a combination with Hall effect10 or van der Pauw11,12 measurements allow separation of the carrier sheet density and mobility contributions to the sheet resistance. The Hall effect characterization, however, usually requires some level of sample preparation, which might even be destructive, e.g., machining of a Greek cross from the sample.4

In this work we show analytically and experimentally that standard micro-four-point probes can be applied to Hall effect measurements on thin films in addition to the conventional sheet resistance measurement application. The only additional requirements are that at least one lateral insulating boundary must be present on the sample and that a strong magnetic field can be applied normal to the sample surface. The theoretical findings are verified experimentally by electrical characterization of highly doped ultrashallow junctions in Si and Ge where sheet resistance, sheet carrier concentration, and Hall mobility are determined.

II. THEORY

In a four-point probe measurement a current \( I_0 \) is forced through the sample surface using two of the four probe pins, while the resulting potential difference is measured between the two remaining probe pins. The current flow in the sample results in an electrostatic potential distribution at the sample surface, \( \Phi(\mathbf{r}) = \Phi(\mathbf{r}, \mathbf{r}_1, \mathbf{r}_2) \), which is a function of the position of interest, \( \mathbf{r} \), the positions of the current injection points, \( \mathbf{r}_1 \) and \( \mathbf{r}_2 \), and the sample geometry and resistivity.

We shall consider primarily the colinear probe pin configurations B and B’, as shown in Fig. 1. In configuration B, the current is forced through the sample from pin No. 1 to pin No. 3, \( \mathbf{r}_1 = \mathbf{r}_3 \), while the potential difference

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between pins Nos. 2 and 4 is measured. In configuration B’ the role of the pins is reversed. It follows that, the measured voltages in configurations B and B’ are

\[ V_B = \Phi(r_2, r_1, r_3) - \Phi(r_4, r_1, r_3), \]

\[ V_{B’} = \Phi(r_1, r_2, r_4) - \Phi(r_3, r_2, r_4), \]

respectively, where \( r_i \) is the in-plane position vector of pin No. \( i \). In micro-four-probe effect measurements the difference, \( \Delta V_{BB} = V_B - V_{B’} \), between these voltages and their average, \( \overline{V_{BB}} = (V_B + V_{B’})/2 \), turns out to be particularly useful. In any case, the essential problem is to find the electrostatic potential \( \Phi(r, r_1, r_2, r_3) \) at the surface of the sample in presence of an applied magnetic flux density.

We shall restrict the analysis to thin, laterally homogenous filamentary samples with insulating boundaries. The sample thickness \( h \) is assumed small compared to the lateral sample dimensions and to the probe pitch. We shall use Cartesian coordinates with base vectors \( e_x, e_y, \) and \( e_z \). Moreover, the magnetic flux density \( B \) is assumed constant and normal to the sample and \( E \) the electric field, \( \mathbf{F}=Ze\mathbf{E}+v_d\times\mathbf{B} \), are normal to the magnetic flux density except in a small region in close proximity of the current injection points; we shall ignore this region since its effect is insignificant on a length scale set by the probe pitch. It follows that the problem of solving for the potential and the electric field is reduced to two dimensions. Here \( Z_e \) is the carrier charge \( (Z_e = \pm 1) \), \( e \) the unit charge, and \( v_d \) the carrier drift velocity. With these simplifications the current density becomes,

\[ \mathbf{J} = \sigma_d \mathbf{E} - \mathbf{Z} \mu_H (\mathbf{B} \times \mathbf{E}), \]

where we have explicitly used the condition \( \mathbf{B} \cdot \mathbf{E} = 0 \). \( \sigma_d \) is the direct conductivity and \( \mu_H \) the Hall mobility, both of these parameters might be dependent on the magnetic flux density magnitude. It follows that a tensorial two-dimensional (2D) conductivity \( \mathbf{\sigma} \) and a corresponding 2D resistivity tensor \( \mathbf{\rho} = \mathbf{\sigma}^{-1} \) can be defined,

\[ \sigma = \begin{bmatrix} \sigma_d & \sigma_H \\ -\sigma_H & \sigma_d \end{bmatrix}, \]

\[ \rho = \begin{bmatrix} \rho_0 & \rho_H \\ -\rho_H & \rho_0 \end{bmatrix}. \]

where the resistivity \( \rho_0 = \left[ \sigma_d (1+\mu_H^2 B^2) \right]^{-1} \), and the Hall conductivity \( \sigma_H = -\sigma_d Z \mu_H B_z \), while the Hall resistivity \( \rho_H = \rho_0 Z \mu_H B_z \).

Conventionally, the Hall coefficient \( R_H \) is used as the primary measured entity in Hall effect measurements. The Hall coefficient \( R_H = \mathbf{E} \cdot (\mathbf{B} \times \mathbf{J})/|\mathbf{B} \times \mathbf{J}|^2 \mathbf{Z} \mu_H [\rho_0 = \rho_H |\mathbf{B}|^2 \mathbf{Z} \mu_H \mathbf{J} \] with the conditions given here.\(^14\) The Hall coefficient has the same sign as the carrier charge and is inversely proportional to the carrier density. Unfortunately the Hall mobility is different from the carrier conductivity mobility \( \mu_c \), where \( r_{H} \) is the Hall scattering factor. The Hall scattering factor is of the order \( 1 \) and accounts for the different statistical averaging needed for the two mobilities, \( r_{H} = \langle \tau_{m}^2 \rangle / \langle \tau_{m} \rangle \), where \( \tau_{m} \) is the momentum relaxation time.

If the thin sample is nonhomogenous in the \( z \) direction, such that \( \sigma_d = \sigma_d(z) \) and \( \mu_H = \mu_H(z) \), the potential remains two dimensional, \( \Phi = \Phi(x, y) \), except in the small region in close proximity of the current injection points. The current density, however, varies in the \( z \)-direction \( \mathbf{J} = \mathbf{J}(x, y, z) \), while \( J_z = 0 \). Integration of Eq. (3) across the thickness of the sample yields the sheet current density \( J_3 = J_3(x, y) \),

\[ J_3 = \int_0^h J dz = \mathbf{E} \int_0^h \sigma_d dz - e_x \times \mathbf{E} \int_0^h \sigma_H dz, \]

where the direct sheet conductance \( G_d \) and the Hall sheet conductance \( G_H \) can be defined as follows:

\[ G_d = \int_0^h \sigma_d dz \text{ and } G_H = \int_0^h \sigma_H dz. \]

With this definition Eq. (5) becomes

\[ J_3 = G_d \mathbf{E} - G_H e_x \times \mathbf{E}. \]

It follows that sheet conductance, \( G_S \), and sheet resistance, \( R_S = G_S^{-1} \), tensors,

\[ G_S = \begin{bmatrix} G_d & G_H \\ -G_H & G_d \end{bmatrix}, \]

\[ R_S = \begin{bmatrix} R_0 & -R_H \\ R_H & R_0 \end{bmatrix}. \]

may be defined, where the direct sheet resistance is \( R_0 = \left[ G_d (1+G_H/G_d) \right]^{-1} \), while the relative Hall sheet resistance equals the relative Hall sheet conductance, \( R_H/R_0 = G_H/G_d \). In analogy to the Hall coefficient a sheet Hall coefficient may be defined as \( R_{HS} = \mathbf{E} \cdot \mathbf{J}_3 / |\mathbf{B} \times \mathbf{J}_3|^2 = R_H/B_z \).

In the homogenous region of interest, \( \Omega \), the sheet current density must be divergence free, \( \nabla \cdot J_3 = 0 \), except at the current injection points, furthermore, the sheet current density normal to the insulating boundary \( \partial \Omega \) must vanish. It follows from Eq. (7) that the electrostatic potential, \( \Phi \), must fulfill

\[ \nabla \cdot J_3 = -G_d \nabla_2^2 \Phi = I_0 [\delta(r - r_+) - \delta(r - r_-)] \text{ in } \Omega, \]
\[ \mathbf{J}_s \cdot \mathbf{n} = (G_y \mathbf{E} - G_H \mathbf{e}_z \times \mathbf{E}) \cdot \mathbf{n} = 0 \quad \text{on } \partial \Omega, \]  
(9)

since \( \mathbf{E} = -\nabla \Phi \), and \( \nabla \cdot (\mathbf{B} \times \mathbf{E}) = \mathbf{E} \cdot (\nabla \times \mathbf{B}) - \mathbf{B} \cdot (\nabla \times \mathbf{E}) = 0 \) for a constant position- and time-independent magnetic flux density. Here \( \mathbf{r} = (x, y) \) is the in-plane position vector, \( \mathbf{r}_a \) and \( \mathbf{r}_b \) are the points where the currents \( \pm I_0 \) are injected, while \( \mathbf{n} \) is the unit vector normal to the lateral insulating boundary \( \partial \Omega \), and \( \delta(\mathbf{r}) \) is Dirac’s delta function. Note the magnetic flux density affects the potential only through the boundary conditions.

In Secs. II A–II C and in the Appendix, we shall solve Eq. (9) for a number of sample geometries relevant to four-probe point measurements; these solutions differ from the solutions given by van der Pauw since the probe pins are assumed to be in the interior of the region \( \Omega \), and not restricted to the perimeter \( \partial \Omega \) as assumed by van der Pauw.

**A. Infinite sheet**

If the lateral boundaries of the sample are infinitely far from the current injection points the potential which solves Eq. (9) is particularly simple, a superposition of two logarithmic potentials

\[ \Phi(\mathbf{r}) = \frac{I_0}{2\pi G_d} \ln \left| \frac{\mathbf{r} - \mathbf{r}_a}{\mathbf{r} - \mathbf{r}_b} \right| = \frac{I_0 R_0}{2\pi} \left( 1 + \frac{R_H^2}{R_0^2} \right) \ln \left| \frac{\mathbf{r}_2 - \mathbf{r}_3}{\mathbf{r}_2 - \mathbf{r}_1} \right|, \]

(10)

which is formally identical to the solution \(^{16}\) for zero magnetic flux density except for the effect of the magnetic flux density on the direct conductivity, \( \sigma_r = \sigma_r(B) \). The current density, however, is different since it is not only a sum of two purely radial current density contributions, two additional tangential current density contributions around each current injection point are also needed.

Using the colinear probe configurations B and B’, as shown in Fig. 1, we find from the potential in Eq. (10) that the measured voltages \( V_B \) and \( V_{B’} \) are equal

\[ V_B = V_{B’} = \frac{I_0 R_0}{2\pi} \left( 1 + \frac{R_H^2}{R_0^2} \right) \ln 3, \]

(11)

a result that is valid for an arbitrary two-dimensional spatial arrangement of the four probe pins. If the probe pins are equidistant with the pitch \( s \), the measured voltages in the two configurations are

\[ V_B = V_{B’} = \frac{I_0 R_0}{2\pi} \left( 1 + \frac{R_H^2}{R_0^2} \right) \ln 3, \]

(12)

a result that except for the factor \( \left( 1 + \frac{R_H^2}{R_0^2} \right) = \left( 1 + \frac{\mu_B^2 B_H^2}{R_0^2} \right) \) is identical to the result at zero magnetic flux density. This factor accounts for part of the magnetoresistance, which at ordinary magnetic flux densities is a quite small effect, except in very high mobility samples. The average Hall mobility \( \mu_H \) is defined in Eq. (24).

**B. Semi-infinite sheet—Upper half-plane**

In the case of the semi-infinite sheet, \( y \geq 0 \), the solution to Eq. (9) can be obtained using the method of images; \(^{17}\) the arrangement of current injection sources and images is shown in Fig. 2. The images, however, must be modified in order to fulfill the boundary condition \( J_s(x,0) = 0 \), since the usual image method would ensure \( E_s(x,0) = 0 \), while \( J_s(x,0) = 0 \) requires \( G_y E_s(x,0) - G_H E_x(x,0) = 0 \) and thus \( E_s(x,0) = (G_H/G_y) E_x(x,0) \).

The potential that solves Eq. (9) in \( \Omega \) is

\[ \Phi(\mathbf{r}) = A_+ \ln \left| \frac{\mathbf{r} - \mathbf{r}_-}{\mathbf{r} - \mathbf{r}_+} \right| + A_- \ln \left| \frac{\mathbf{r} - \mathbf{r}_+}{\mathbf{r} - \mathbf{r}_-} \right| + \frac{I_0 R_H}{\pi} \left( \arctan \frac{x - x_+}{y + y_+} - \arctan \frac{x - x_-}{y + y_-} \right), \]

(13)

where \( \mathbf{r}_\pm = (x_\pm, y_\pm) = (x_\pm, y_\pm) \) are the positions of the modified images of the sources at positions \( \mathbf{r}_\pm \). The first term is the source term, while the two remaining terms originate from the images, they are thus due to the boundary conditions at \( y = 0 \). For each of the current sources the boundary conditions are fulfilled by combining a source term representing a purely radial electric field with image terms representing a purely radial current density. For later convenience the coefficients \( A_+ \) and \( A_- \) have been defined as follows:

\[ A_+ = \frac{I_0 R_0}{2\pi} \left( 1 + \frac{R_H^2}{R_0^2} \right), \]

(14)

\[ A_- = \frac{I_0 R_0}{2\pi} \left( 1 - \frac{R_H^2}{R_0^2} \right). \]

Using Eqs. (1) and (2) the measured voltages in probe configurations B and B’ are calculated (the overbar in, e.g., \( \mathbf{r}_\bar{\pm} \) is used as an operator). From these the voltage difference \( \Delta V_{BB’} \) results

\[ \Delta V_{BB’} = \frac{2I_0 R_H}{\pi} \left( \arctan \frac{x_2 - x_1}{y_2 + y_1} + \arctan \frac{x_3 - x_2}{y_3 + y_2} \right. \]

\[ + \left. \arctan \frac{x_4 - x_3}{y_4 + y_3} - \arctan \frac{x_4 - x_1}{y_4 + y_4} \right), \]

(15)

while the average voltage \( V_{BB’} \) becomes
the four probe pins are positioned at $A$, $B$, $B'$, and $C$, arranged in configurations B and B', with equidistant, colinear four-point probe pins aligned parallel to the $x$ axis such that the four probe pins are positioned at $(i x, y_0)$, $i \in \{0, 1, 2, 3\}$, arranged in configurations B and B', the measured voltages $V_B$ and $V_B'$ can be combined as follows:

$$\Delta V_{BB'} = \frac{2 I_0 R_H}{\pi} \left( \frac{s}{2 y_0} - \frac{3 s}{2 y_0} \right)$$

and

$$V_{BB'} = A_+ \ln 3 + A_- \ln \sqrt{9 + \frac{4 \left(\frac{y_0}{y}\right)^2}{1 + \frac{4 \left(\frac{y_0}{y}\right)^2}}}. \quad (17)$$

From Eq. (17) the Hall sheet resistance $R_H$ can be extracted using measured data as a function of distance to the boundary, thereafter the direct sheet resistance $R_0$ can be determined using Eq. (18).

In Fig. 3, $(V_B - V_{B'})/I_0 R_H$, calculated from Eqs. (17) and (15), is shown as a function of the normalized distance $y_0/s$ of the probe center to the boundary at $y=0$, where $V_B - V_{B'} = 2 I_0 R_H$. Calculations for four different angles, $\theta \in \{0, \pi/16, \pi/8, \pi/4\}$, between the line of probe pins and the insulating boundary; the line of the probe pins and the boundary are parallel at $\theta=0$.

$${V_{BB'}^2} = \frac{I_0 R_0}{2\pi} \left( 1 + \frac{R_H^2}{R_0^2} \right) \ln \left| \frac{r_2 - r_3}{r_2 - r_1} \frac{r_4 - r_3}{r_4 - r_1} \right|$$

$$+ \frac{I_0 R_0}{2\pi} \left( 1 - \frac{R_H^2}{R_0^2} \right) \ln \left| \frac{r_2 - r_3}{r_2 - r_1} \frac{r_4 - r_3}{r_4 - r_1} \right|. \quad (16)$$

These equations are valid for any arbitrary spatial probe pin arrangement.

In a practical measurement, with equidistant, colinear four-point probe pins aligned parallel to the $y$ axis such that the four probe pins are positioned at $(i x, y_0)$, $i \in \{0, 1, 2, 3\}$, arranged in configurations B and B', the measured voltages $V_B$ and $V_B'$ can be combined as follows:

$$\Delta V_{BB'} = \frac{2 I_0 R_H}{\pi} \left( \frac{s}{2 y_0} - \frac{3 s}{2 y_0} \right)$$

and

$$V_{BB'} = A_+ \ln 3 + A_- \ln \sqrt{9 + \frac{4 \left(\frac{y_0}{y}\right)^2}{1 + \frac{4 \left(\frac{y_0}{y}\right)^2}}}. \quad (18)$$

From Eq. (17) the Hall sheet resistance $R_H$ can be extracted using measured data as a function of distance to the boundary, thereafter the direct sheet resistance $R_0$ can be determined using Eq. (18).

In Fig. 3, $(V_B - V_{B'})/I_0 R_H$, calculated from Eqs. (17) and (15), is shown as a function of the normalized distance $y_0/s$ of the probe center to the boundary at $y=0$, where $V_B - V_{B'} = 2 I_0 R_H$. Calculations for four different angles, $\theta \in \{0, \pi/16, \pi/8, \pi/4\}$, between the line of probe pins and the boundary are shown; at the angle $\theta=\pi/2$ the Hall voltage contribution vanishes, $\Delta V_{BB'}=0$. The measured voltage difference is seen to be significant only very close to the boundary and vanish if the distance is more than a few times the probe pitch. The effect of a small angular misalignment between the probe and the boundary is seen to be very small in the case where parallel probe and boundary is wanted.

In Fig. 4, $(V_B + V_{B'}) \pi/(I_0 R_0 \ln 3)$, calculated from Eq. (18) is shown as a function of the normalized distance $y_0/s$ from the boundary $y=0$ at three values of the relative Hall resistance, $R_H/R_0$. The sum of the measured voltages is independent on the relative Hall resistance close to the boundary, where the measured value, $V_B + V_{B'} = (R_0/0 \ln 3)/\pi$, is twice the value measured very far from the edge at zero magnetic flux density. Far from the edge the full effect of the magnetoresistance affects the sum of the measured voltages. Equation (18) is reminiscent of the usual single insulating boundary proximity correction for four-point probe sheet resistance measurements on thin films.18,19

C. Narrow stripe

The potential in the stripe $0 \leq y \leq w$ with insulating boundaries at $y=0$ and $y=w$ can be found from an infinite sum of alternating modified and ordinary images. The sources and ordinary images are positioned at $r_{ni} + 2n w$, where the vector $w=w e_y$, and $n$ is an arbitrary integer, while the modified images are positioned at $\bar{r}_{ni} + 2n w$, as illustrated in Fig. 5.

The potential that solves Eq. (9) in $\Omega$ is

$$\Phi(r) = A_+ \sum_{n=\infty}^{\infty} \ln \left| \frac{r - r_{-2n w}}{r - r_{-2n w}} \right|$$

$$+ A_- \sum_{n=\infty}^{\infty} \ln \left| \frac{r - \bar{r}_{-2n w}}{r - \bar{r}_{-2n w}} \right|$$

$$+ \frac{I_0 R_H}{\pi} \sum_{n=\infty}^{\infty} \left( \arctan \frac{x - x_+}{y + y_+ - 2n w} - \arctan \frac{x - x_-}{y + y_- - 2n w} \right). \quad (19)$$
From this potential, the measured voltages, \( V_B \) and \( V_{B'} \), in configuration B and \( B' \) can be calculated using Eqs. (1) and (2); these voltages can be subtracted or added to yield

\[
\Delta V_{BB'} = \frac{2I_0 R_H}{\pi} \sum_{n=-\infty}^{\infty} \left( \frac{\arctan \frac{x_2-x_1}{y_2+y_1-2nw}}{n+1} \right.
\]

\[+ \frac{\arctan \frac{x_3-x_2}{y_3+y_2-2nw}}{n+1} \left. + \frac{\arctan \frac{x_4-x_3}{y_4+y_3-2nw}}{n+1} \right) - \frac{\arctan \frac{x_4-x_1}{y_4+y_1-2nw}}{n+1}, \tag{20}
\]

and

\[
\overline{V_{BB'}} = A_+ \sum_{n=-\infty}^{\infty} \ln \left| \frac{r_2-r_3-2nw}{r_2-r_1-2nw} \right| - \frac{\arctan \frac{3s}{2y_0-2nw}}{2y_0-2nw}, \tag{22}
\]

\[
= A_- \sum_{n=-\infty}^{\infty} \ln \left| \frac{r_2-r_3-2nw}{r_2-r_1-2nw} \right| - \frac{\arctan \frac{3s}{2y_0-2nw}}{2y_0-2nw} \tag{23}
\]

In Fig. 6, \((V_B-V_{B'})/(I_0 R_H)\), calculated from Eq. (22) is shown as a function of the normalized distance \( y_0/s \) from the boundary \( y=0 \) for a stripe of width \( w=5s \); the measured voltage difference is seen to be significant only very close to the boundaries and vanish if the distance from each boundary is more than a few times the probe pitch. For comparison, results for a half-plane, Eq. (17), is also shown for comparison; this simple result is quite similar to the result for the stripe close to the left boundary. Finally, the approximation resulting from using only the first two terms in the infinite sum of Eq. (22) is shown, but cannot be distinguished from the full solution.

In Fig. 7, \((V_B+V_{B'})/(I_0 R_H \ln 3)\), calculated from Eq. (23), is shown as a function of the normalized distance \( y_0/s \).
from the boundary \( y = 0 \) for a stripe of width \( w = 5s \) at three values of the relative Hall sheet resistance \( R_{H}/R_0 \). The sum of the measured voltages is independent on the relative Hall sheet resistance close to the boundary. Far from the edge the full effect of the magnetoresistance affects the sum of the measured voltages. The finite width of the stripe affects the sum of the measured voltages at all positions as seen from a comparison with the result for a half-plane, Eq. (18), which is also shown in Fig. 7 for convenience.

D. Interpretation of Hall effect measurements

The primary applications of Hall effect measurements on semiconductor samples are experimental characterization of Hall mobility and carrier concentration. For a homogenous sample, the Hall mobility can be calculated from the measured quantities, the Hall conductivity \( G_H \), the direct conductivity \( \sigma_d \) (or the respective resistivities), and the magnetic flux density, since \( \mu_H = \frac{\sigma_d}{\sigma_d + \sigma_H} = \frac{\rho_H}{\rho_d} \). The Hall mobility can also be calculated from the Hall coefficient \( \mu_H = \frac{R_H}{\rho_d} \). For a sample with carrier density, \( n = n(z) \), and thus mobility variations in the \( z \) direction a mean Hall mobility, \( \bar{\mu}_H \), can be calculated from the measured Hall sheet conductance, \( G_H \), and direct sheet conductance, \( G_d \); according to \( 20 \)

\[
\bar{\mu}_H = \frac{G_H}{G_d} = \frac{1}{\int_0^h n \mu_H dz} = \frac{R_H}{R_0},
\]

where Eq. (6) and \( \sigma_d = e \mu \) have been used. The equation \( \sigma_d = e \mu \) is valid at sufficiently low magnetic flux densities.

For a homogenous sample the carrier density is then \( n = \frac{\rho_H}{\rho_d} \), and the carrier mobility becomes \( \frac{\rho_H}{\rho_d} \). Using relations between resistivities and conductivities the carrier density becomes \( n = \frac{\rho_H}{\rho_d} \), and the carrier mobility becomes \( \frac{\rho_H}{\rho_d} \). Using relations between resistivities and conductivities the carrier density becomes \( n = \frac{\rho_H}{\rho_d} \), and the carrier mobility becomes \( \frac{\rho_H}{\rho_d} \).

The treatment given here only apply to samples that are homogenous in the \( x-y \) plane; a nonhomogenous sample is a far more difficult problem. \( 21 \)

III. EXPERIMENTS

Microscale Hall effect measurements were performed with a micro-four-point probe (M4PP) using a CAPRES microRSP-M150 (Ref. 22) system. The M4PP used in these experiments consists of metal coated silicon cantilever electrodes extending from the edge of a silicon die; Fig. 8 shows a scanning electron microscope (SEM) image of a M4PP die with a close up image of the probe cantilevers shown in the inset. In the experiments Ni coated as well as Au coated M4PP’s were used. For the microscale Hall measurements, the sample chuck of the microRSP-M150 was fitted with a permanent magnet. The resulting magnetic flux density at the position of the sample was \( B_z = 0.5 \text{ T} \) as measured using a calibrated Hall sensor.

To explore the potential of the new microscale Hall effect method, highly doped \( p \)-type silicon and \( p \)-type germanium samples with single and double insulating barrier geometry, respectively, were characterized. These samples are particularly challenging to characterize due to the rather low mobilities and therefore small relative Hall sheet resistances.

First, the sheet resistance is measured far from the insulating barrier (more than three times the electrode pitch) using dual configuration position correction. \( 4 \) This is done to determine the sheet resistance more accurately; dual configuration measurements typically allow for sheet resistance repeatability with a standard deviation on the order of 0.1%, whereas the relative standard deviation of a single configuration measurement is an order of magnitude higher depending on the electrode pitch. \( 21 \)

Then the M4PP is aligned parallel to an insulating boundary, i.e., the tips of the electrodes are positioned at \( (i \delta, y_0) \), \( i \in \{0, 1, 2, 3\} \), while the insulating boundary is situated at \( y = y_0 \). After optical alignment, the probe is repeat-
edly engaged with the surface and moved to a new position in a direction perpendicular to the insulating boundary. During each engage, a series of four-point resistance measurements in configurations B and B’ are performed using a measurement current set-point of \( I_0 = 100 \, \mu A \). The measurement noise on \( \Delta V_{BB'} = (V_B - V_{B'}) \) is reduced by averaging the measurements during each engage.

Finally, the Hall sheet resistance \( R_H \) and the exact boundary position \( y_{00} \) in the probe coordinate system are estimated by fitting to the measured data the appropriate analytical model for the specific geometry, Eqs. (17) or (22), using a nonlinear fitting algorithm.\(^24\) Thereafter, the Hall sheet resistance \( R_H \) and standard deviation \( \Delta R_H \) is calculated using a linear regression where the positions \( y_0 \) and \( y_{00} \) are used with the analytical model to calculate a nonlinear position axis where a linear relation to \( \Delta V_{BB'} \) is expected.

### IV. RESULTS AND DISCUSSION

In the Secs. IV A and IV B, where measurements on ultrashallow junctions in silicon and germanium are reported, we experimentally verify the microscale Hall effect method. A comparative experimental study of this method and alternative characterization methods on ultrashallow junctions is in progress.

#### A. Silicon—Single barrier

An ultrashallow junction was formed in an \( n \)-type (100) silicon wafer by low energy boron implantation (3 keV, \( 1 \times 10^{15} \, \text{cm}^{-2} \)) followed by rapid thermal annealing (RTA). The nonpatterned wafer was cleaved to provide a well-defined straight insulating boundary. The dual configuration sheet resistance measured on the sample was \( 267.1 \pm 0.8 \, \Omega \), where the uncertainty is mainly due to sample nonhomogeneity.

On this sample microscale Hall effect measurements were performed under various experimental conditions. For this sample the Hall resistance measurement data were filtered through a simple 40% median filter to eliminate severe measurement outliers (each probe position treated separately) prior to averaging. This was necessary due to measurement noise, probably related to the electrode-sample contact properties.

Figure 9 shows Hall effect measurement data (●) using a 30 \( \mu m \) pitch Au coated M4PP; the full line shows the model fit to the measured data, corresponding to a Hall sheet resistance, \( R_H = 0.562 \pm 0.005 \, \Omega \), and the estimated boundary position, \( y_{00} = 0.22 \, \mu m \). Hall effect measurements were done using both Au and Ni coated M4PP’s in order to investigate if application of a ferromagnetic electrode metal would affect the measurement. Likewise, the effect of electrode pitch and measurement frequency was investigated by performing measurements also using a 10 \( \mu m \) pitch M4PP and by measurements at 11 Hz as well as 987 Hz. The Hall sheet resistances and the corresponding standard deviations extracted from model fits to measurement data are summarized in Table I, where no significant effect of the various experimental conditions is seen. The repeatability even with significant alterations of the experimental conditions is very good, the relative standard deviation on the average of the measurements in Table I is less than 1.5%. The minimum number of measurement points necessary for an accurate extraction of the Hall sheet resistance has not been investigated, but a trade-off between precision and measurement time exists; the total data acquisition time used to produce the data in Fig. 9 was 5 min.

From the measured Hall sheet resistance and sheet resistance of the sample both active Hall sheet carrier density, \( N_{HS} \), and average Hall mobility, \( \mu_{H} \), were calculated using Eqs. (24) and (25), however, since the effective Hall scattering factor is not known \( \tau_H = 1 \) is assumed. The results are summarized in Table I. The calculated active dose is approximately half of the implanted dose; this is in agreement with the expected value since the boron concentration is above the solid solubility and partial dose activation therefore expected. Finally, the Hall mobility is within 10% of the Hall mobility reported by Sasaki for highly boron doped silicon.\(^25\)

#### B. Germanium—Double barrier

Microscale Hall effect measurements were also performed on a patterned shallow \( p \)-type junction (80 nm) formed in Ge using RTA of a boron implant (10 keV, \( 2 \times 10^{15} \, \text{cm}^{-2} \)) following a preamorphization implant. The pattern used for the measurements was a double insulating barrier with a nominal distance between barriers of 100 \( \mu m \). Figure 10 illustrates the measurement setup. In the measurements a 20 \( \mu m \) pitch M4PP probe was used at a measurement frequency of 11 Hz. For this sample data were not filtered. Figure 11 shows the measured Hall resistance data (●) resulting from a line scan across the \( p \)-type stripe; the full line shows a model fit—using Eq. (22)—to measured data with the Hall sheet resistance, \( R_H \), the position of the left boundary, \( y_{00} \), and the width of the stripe, \( w \), as fitting parameters.
The experimental results are summarized in Table II. The high precision obtained for the direct sheet resistance \( R_{SH} = 63.63 \pm 0.02 \, \Omega \) does not include sample variations since the measurements were performed at a single position. The low standard deviation on the Hall sheet resistance \( \Delta R_{SH} = 0.002 \, \Omega \) demonstrates the high reproducibility of M4PP measurements on p-type Ge. The calculated active Hall sheet carrier density \( N_{HS} = (1.18 \pm 0.01) \times 10^{15} \, \text{cm}^{-2} \) is in good agreement with the expected value considering the implanted dose. The calculated Hall mobility \( \mu_{SH} = 83.0 \pm 0.6 \, \text{cm}^2 \, \text{V}^{-1} \, \text{s}^{-1} \) is in agreement with values reported by Golikova et al.\(^{26}\)

<table>
<thead>
<tr>
<th>( s ) (( \mu \text{m} ))</th>
<th>( f ) (Hz)</th>
<th>( R_{SH} \pm \Delta R_{SH} ) (( \Omega ))</th>
<th>( N_{HS} \pm \Delta N_{HS} ) ( \times 10^{14} , \text{cm}^{-2} )</th>
<th>( \mu_{SH} \pm \Delta \mu_{SH} ) ( \text{cm}^2 , \text{V}^{-1} , \text{s}^{-1} )</th>
</tr>
</thead>
<tbody>
<tr>
<td>Au</td>
<td>30</td>
<td>11</td>
<td>0.562 ( \pm ) 0.005</td>
<td>5.55 ( \pm ) 0.05</td>
</tr>
<tr>
<td>Ni</td>
<td>10</td>
<td>11</td>
<td>0.570 ( \pm ) 0.015</td>
<td>5.48 ( \pm ) 0.14</td>
</tr>
<tr>
<td>Ni</td>
<td>30</td>
<td>11</td>
<td>0.556 ( \pm ) 0.008</td>
<td>5.61 ( \pm ) 0.08</td>
</tr>
<tr>
<td>Ni</td>
<td>30</td>
<td>987</td>
<td>0.551 ( \pm ) 0.003</td>
<td>5.66 ( \pm ) 0.03</td>
</tr>
</tbody>
</table>

V. CONCLUSION

Carrier sheet concentration and mobility are key parameters with a strong effect on semiconductor device performance. Conventional measurements of these parameters become increasingly difficult with the continued miniaturization of CMOS devices, in particular for the ultrashallow junctions required; these parameters nevertheless need to be characterized for process development and control purposes. In this work we demonstrate for the first time that M4PP’s can be used to measure Hall mobility and sheet carrier concentration with little or no additional sample preparation.

The electrostatic potential due to the injected current and applied magnetic flux density is derived for an infinite sheet, a semi-infinite sheet, a narrow stripe, a quarter-plane, and a rectangle. With one or more insulating lateral boundaries present Hall effect affects the potential; without the insulating boundary only magnetoresistance is seen.

The voltage measured with a colinear, equidistant four-point probe is derived for the semi-infinite sheet and the narrow stripe sample geometries. The Hall effect contribution is separated from magnetoresistance and sheet resistance by dual configuration difference and sum methods, respectively. Finally, the sensitivity of the Hall effect signal to small angular misalignment between a four-point probe and an insulating boundary is shown to be virtually zero, which is ideal for experiments.

The theory is verified by experiments on ultrashallow implanted junctions in Si and Ge. The measured sheet carrier concentration and Hall mobility are shown to be reproducible and virtually unaffected by changes in electrode material (diamagnetic versus ferromagnetic), electrode pitch, and measurement frequency.

The microscale Hall effect measurement method has several interesting potential applications since Hall mobility and sheet carrier density may be measured (i) with high spatial resolution, (ii) without the need for lithographically defined metal contacts, (iii) on fragile samples where postpro-
and Hall mobility, and modified image positions. The potential that solves Eq.
013710-9 Petersen et al. calculated; due to the limited space, however, we do not report
these equations.

ACKNOWLEDGMENTS

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APPENDIX: QUARTER-PLANE AND RECTANGLE

Consider now the upper right quarter plane \(x \geq 0\) and \(y \geq 0\), see Fig. 12. The sources at \(r_s\) must be combined with ordinary images at \(-r_s\) and modified images at \(\pm r_{s*}\), where \(r_{s*}=(x_{s*}, y_{s*})=(x_s, -y_s)\) again are the y-axis mirrored modified image positions. The potential that solves Eq. (9) in \(\Omega\) is thus

\[
\Phi(r) = A_+ \sum_{n=-\infty}^{\infty} \sum_{m=-\infty}^{\infty} \ln \frac{\lvert r - r_s - 2(nw + m\ell) \rvert}{\lvert r - r_s - 2(nw + m\ell) \rvert} + A_- \ln \frac{\lvert r - r_s + 2(nw + m\ell) \rvert}{\lvert r - r_s + 2(nw + m\ell) \rvert} \\
+ \frac{I_{0} R_H}{\pi} \sum_{n=-\infty}^{\infty} \sum_{m=-\infty}^{\infty} \left( \arctan \frac{x - x_s - 2m\ell}{y + y_s - 2nw} - \arctan \frac{x - x_s - 2m\ell}{y + y_s - 2nw} \right) + \frac{I_{0} R_H}{\pi} \sum_{n=-\infty}^{\infty} \sum_{m=-\infty}^{\infty} \left( \arctan \frac{y - y_s - 2nw}{x + x_s - 2m\ell} - \arctan \frac{y - y_s - 2nw}{x + x_s - 2m\ell} \right).
\]

Here the first term is due to the sources and ordinary images, while the remaining terms are due to the modified images.

From Eqs. (A1) or (A2) the measured voltages in configurations B and B’ and thus \(\Delta V_{BB}\) and \(\bar{V}_{BB}\) may be calculated; due to the limited space, however, we do not report these equations.


\[
\begin{array}{c}
\bar{V}_{BB} = V_{BB} - \Delta V_{BB}.
\end{array}
\]
(2008).


